National Semiconductor

May 1995

54F/74F574
Octal D-Type Flip-Flop with TRI-STATE® Outputs

General Description

The 'F574 is a high-speed, low power octal flip-flop with a buffered common Clock (CP) and a buffered common Output Enable ($\overline{OE}$). The information presented to the D inputs is stored in the flip-flops on the LOW-to-HIGH Clock (CP) transition.

This device is functionally identical to the 'F374 except for the pinouts.

Features

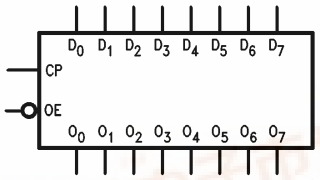
- Inputs and outputs on opposite sides of package allowing easy interface with microprocessors
- Useful as input or output port for microprocessors
- Functionally identical to 'F374
- TRI-STATE outputs for bus-oriented applications

Commercial	Military	Package Number	Package Description
74F574PC		N20A	20-Lead (0.300″ Wide) Molded Dual-In-Line
	54F574DM (Note 2)	J20A	20-Lead Ceramic Dual-In-Line
74F574SC (Note 1)		M20B	20-Lead (0.300″ Wide) Molded Small Outline, JEDEC
74F574SJ (Note 1)		M20D	20-Lead (0.300″ Wide) Molded Small Outline, EIAJ
	54F574FM (Note 2)	W20A	20-Lead Cerpack
	54F574LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

Note 1: Devices also available in 13″ reel. Use suffix = SCX and SJX.

Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

Logic Symbols



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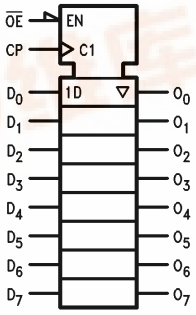
IEEE/IEC



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Unit Loading/Fan Out

Pin Names	Description	54F/74F	
		U.L. HIGH/LOW	Input I_{IH}/I_{IL} Output I_{OH}/I_{OL}
D_0–D_7	Data Inputs	1.0/1.0	20 μA/−0.6 mA
CP	Clock Pulse Input (Active LOW)	1.0/1.0	20 μA/−0.6 mA
$\overline{OE}$	TRI-STATE Output Enable Input (Active LOW)	1.0/1.0	20 μA/−0.6 mA
O_0–O_7	TRI-STATE Outputs	150/40 (33.3)	−3 mA/24 mA (20 mA)

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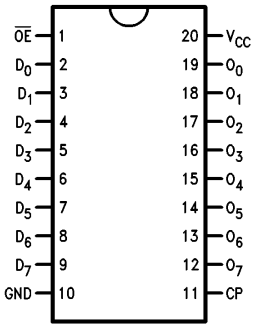
Connection Diagrams

Pin Assignment for DIP, SOIC and Flatpak



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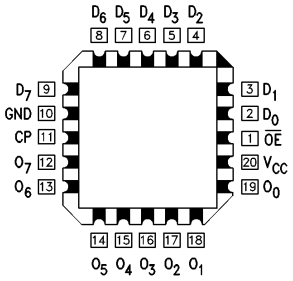
Pin Assignment for LCC



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Functional Description

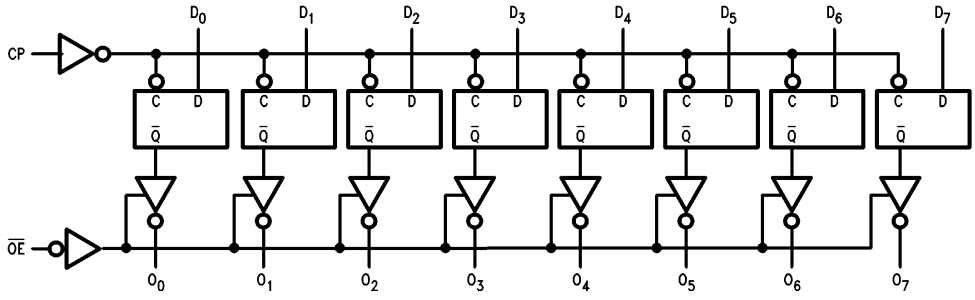
The 'F574 consists of eight edge-triggered flip-flops with individual D-type inputs and TRI-STATE true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold times requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable ($\overline{OE}$) LOW, the contents of the eight flip-flops are available at the outputs. When $\overline{OE}$ is HIGH, the outputs go to the high impedance state. Operation of the $\overline{OE}$ input does not affect the state of the flip-flops.

Function Table

Inputs			Internal	Outputs	Function
$\overline{OE}$	CP	D	Q	O	
H	H	L	NC	Z	Hold
H	H	H	NC	Z	Hold
H	↗	L	L	Z	Load
H	↗	H	H	Z	Load
L	↗	L	L	L	Data Available
L	↗	H	H	H	Data Available
L	H	L	NC	NC	No Change in Data
L	H	H	NC	NC	No Change in Data

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance
↗ = LOW-to-HIGH Transition
NC = No Change

Logic Diagram



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Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	−65°C to +150°C
Ambient Temperature under Bias	−55°C to +125°C
Junction Temperature under Bias	−55°C to +175°C
Plastic	−55°C to +150°C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V_{CC} = 0V)	
Standard Output	−0.5V to V_{CC}
TRI-STATE Output	−0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I_{OL} (mA)

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature	
Military	−55°C to +125°C
Commercial	0°C to +70°C
Supply Voltage	
Military	+4.5V to +5.5V
Commercial	+4.5V to +5.5V

DC Electrical Characteristics

Symbol	Parameter		54F/74F Min	54F/74F Typ	54F/74F Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V_{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal
V_{CD}	Input Clamp Diode Voltage				−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	54F 10% V_{CC}	2.5			V	Min	I_{OH} = −1 mA
		54F 10% V_{CC}	2.4					I_{OH} = −3 mA
		74F 10% V_{CC}	2.5					I_{OH} = −1 mA
		74F 10% V_{CC}	2.4					I_{OH} = −3 mA
		74F 5% V_{CC}	2.7					I_{OH} = −1 mA
		74F 5% V_{CC}	2.7					I_{OH} = −3 mA
V_{OL}	Output LOW Voltage	54F 10% V_{CC}			0.5	V	Min	I_{OL} = 20 mA
		74F 10% V_{CC}			0.5			I_{OL} = 24 mA
I_{IH}	Input HIGH Current	54F			20.0	μA	Max	V_{IN} = 2.7V
		74F			5.0			
I_{BVI}	Input HIGH Current Breakdown Test	54F			100	μA	Max	V_{IN} = 7.0V
		74F			7.0			
I_{CEX}	Output HIGH Leakage Current	54F			250	μA	Max	V_{OUT} = V_{CC}
		74F			50			
V_{ID}	Input Leakage Test	74F	4.75			V	0.0	I_{ID} = 1.9 μA All Other Pins Grounded
I_{OD}	Output Leakage Circuit Current	74F			3.75	μA	0.0	V_{IOD} = 150 mV All Other Pins Grounded
I_{IL}	Input LOW Current				−0.6	mA	Max	V_{IN} = 0.5V
I_{OZH}	Output Leakage Current				50	μA	Max	V_{OUT} = 2.7V
I_{OZL}	Output Leakage Current				−50	μA	Max	V_{OUT} = 0.5V
I_{OS}	Output Short-Circuit Current		−60		−150	mA	Max	V_{OUT} = 0V
I_{ZZ}	Bus Drainage Test				500	μA	0.0V	V_{OUT} = 5.25V
I_{CCZ}	Power Supply Current			55	86	mA	Max	V_O = HIGH Z

AC Electrical Characteristics

Symbol	Parameter	74F $T_A = +25°C$ $V_{CC} = +5.0V$ $C_L = 50$ pF			54F $T_A, V_{CC} =$ Mil $C_L = 50$ pF		74F $T_A, V_{CC} =$ Com $C_L = 50$ pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
f_{max}	Maximum Clock Frequency	100			60		70		MHz
t_{PLH}	Propagation Delay	2.5	5.3	8.5	2.5	9.5	2.5	8.5	ns
t_{PHL}	CP to O_n	2.5	5.3	8.5	2.5	9.5	2.5	8.5	
t_{PZH}	Output Enable Time	3.0	5.5	9.0	2.5	10.5	2.5	10.0	ns
t_{PZL}		3.0	6.0	9.0	2.5	10.5	2.5	10.0	
t_{PHZ}	Output Disable Time	1.5	3.3	5.5	1.5	7.0	1.5	6.5	
t_{PLZ}		1.5	2.8	5.5	1.5	7.0	1.5	6.5	

AC Operating Requirements

Symbol	Parameter	74F $T_A = +25°C$ $V_{CC} = +5.0V$		54F $T_A, V_{CC} =$ Mil		74F $T_A, V_{CC} =$ Com		Units
		Min	Max	Min	Max	Min	Max	
$t_s(H)$	Set-up Time, HIGH or LOW	2.5		3.0		2.5		ns
$t_s(L)$	D_n to CP	2.0		2.5		2.0		
$t_h(H)$	Hold Time, HIGH or LOW	2.0		2.0		2.0		
$t_h(L)$	D_n to CP	2.0		2.0		2.0		
$t_w(H)$	CP Pulse Width	5.0		5.0		5.0		ns
$t_w(L)$	HIGH or LOW	5.0		5.0		5.0		

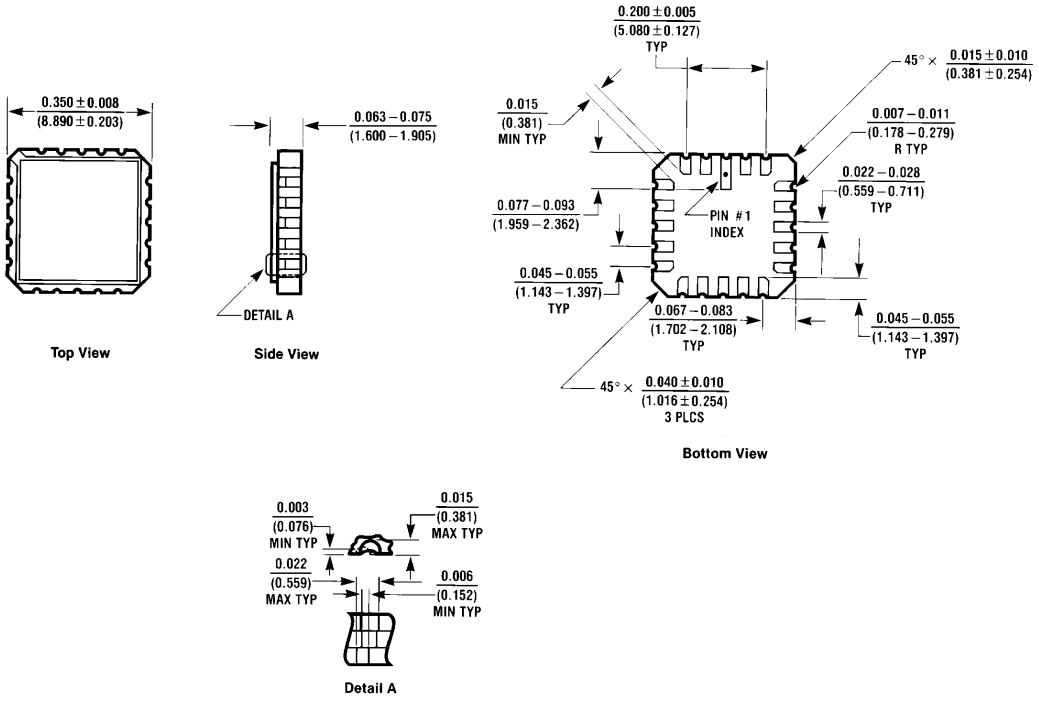
Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:

74F 574 S C X

- Temperature Range Family
  - 74F = Commercial
  - 54F = Military
- Device Type
- Package Code
  - P = Plastic DIP
  - D = Ceramic DIP
  - F = Flatpak
  - L = Leadless Chip Carrier (LCC)
  - S = Small Outline JEDEC
  - SJ = Small Outline SOIC EIAJ
- Temperature Range
  - C = Commercial (0°C to +70°C)
  - M = Military (−55°C to +125°C)
- Special Variations
  - QB = Military grade device with environmental and burn-in processing

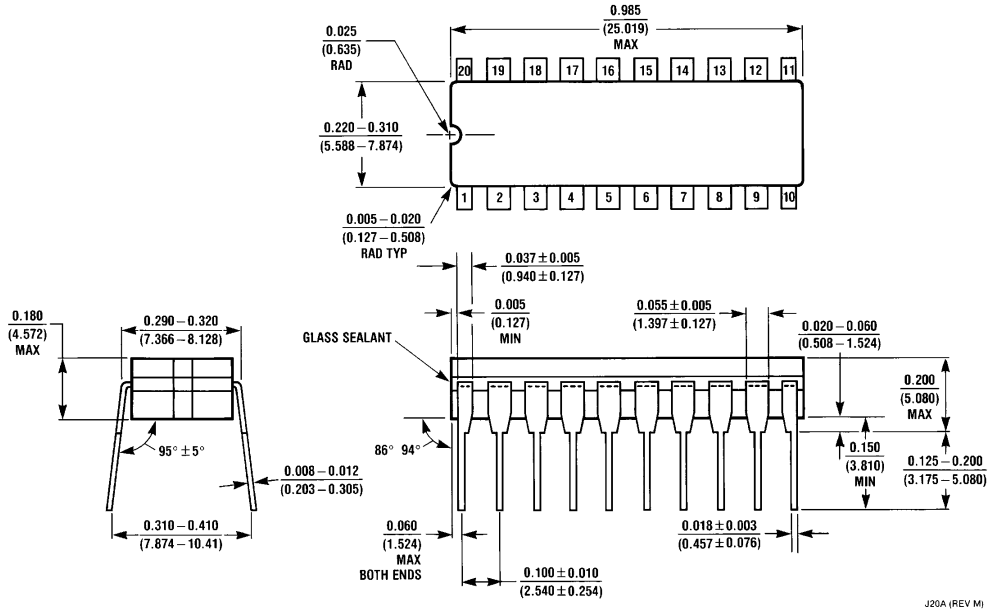
Physical Dimensions inches (millimeters)



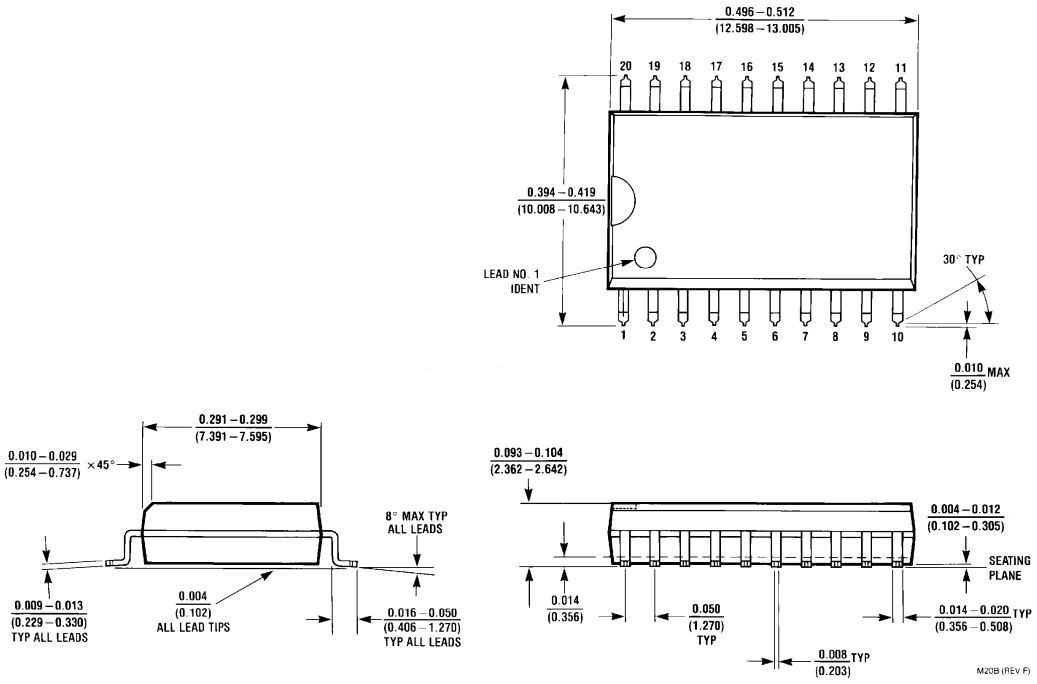
E20A (REV D)

20-Lead Ceramic Leadless Chip Carrier (L)
NS Package Number E20A

Physical Dimensions inches (millimeters) (Continued)

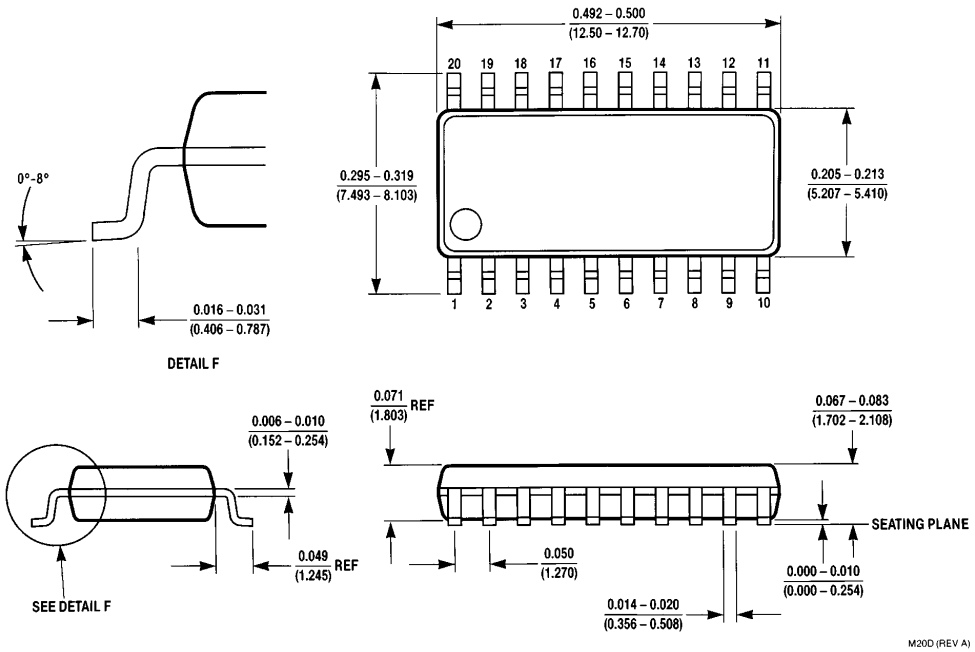


20-Lead Ceramic Dual-In-Line Package (D)
NS Package Number J20A

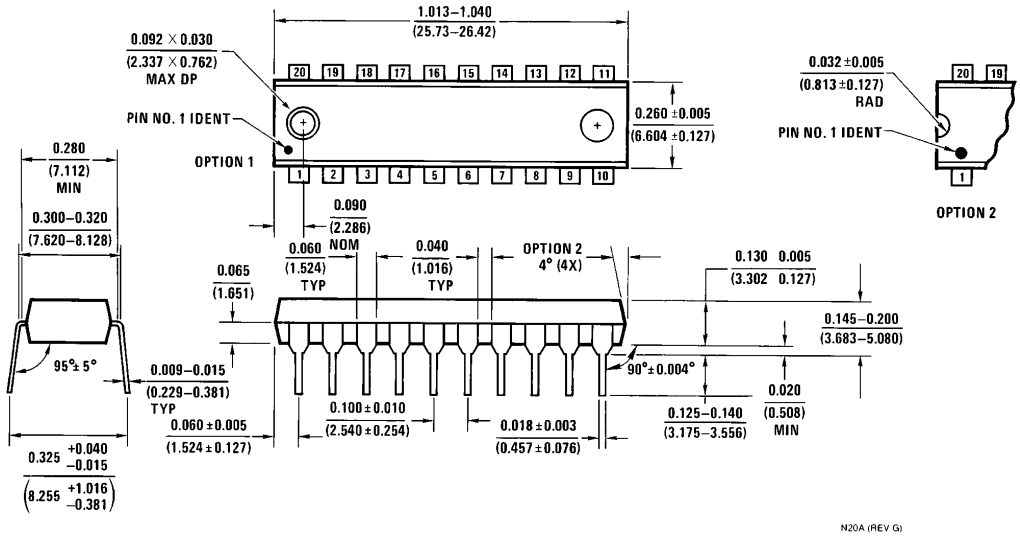


20-Lead (0.300″ Wide) Molded Small Outline Package, JEDEC (S)
NS Package Number M20B

Physical Dimensions inches (millimeters) (Continued)

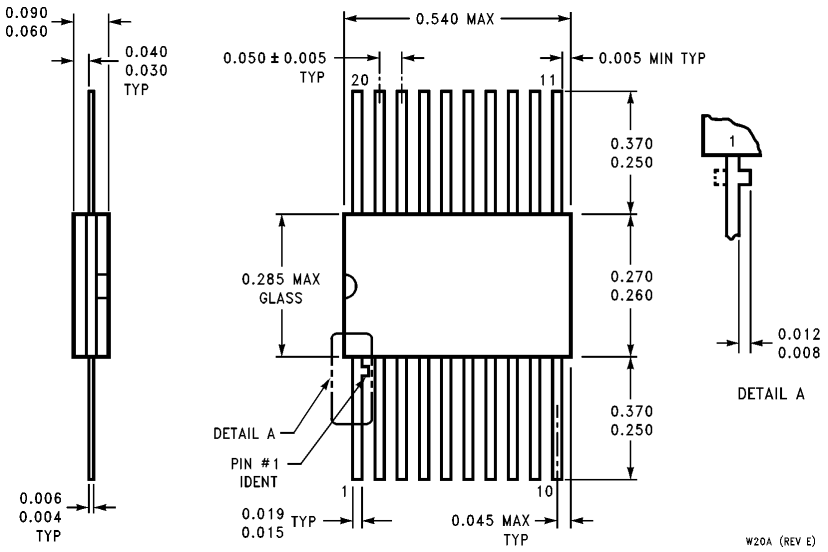


20-Lead (0.300″ Wide) Molded Small Outline Package, EIAJ
NS Package Number M20D



20-Lead (0.300″ Wide) Molded Dual-In-Line Package (P)
NS Package Number N20A

Physical Dimensions inches (millimeters) (Continued)



20-Lead Ceramic Flatpak (F)
NS Package Number W20A

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